

Soldering temperature, 1.6mm (0.063 in.) from case for 10s	-	260	
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Thermal Resistance

Parameter	Symbol	Conditions	Max. Value	Unit
Characteristic				
IGBT thermal resistance, junction – case	R_{thJC}		1.1	K/W
Diode thermal resistance, junction – case	R_{thJCD}		1.5	
Thermal resistance, junction – ambient	R_{thJA}		40	

Electrical Characteristic, at $T_j = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
Static Characteristic						
Collector-emitter breakdown voltage	$V_{(BR)CES}$	$V_{GE}=0V, I_C=0.5mA$	1200	-	-	V
Collector-emitter saturation voltage	$V_{CE(sat)}$	$V_{GE} = 15V, I_C=15A$				
		$T_j=25^{\circ}C$	-	1.7	2.2	
		$T_j=125^{\circ}C$	-	2.0	-	
		$T_j=150^{\circ}C$	-	2.2	-	
Diode forward voltage	V_F	$V_{GE}=0V, I_F=15A$				
		$T_j=25^{\circ}C$	-	1.7	2.2	
		$T_j=125^{\circ}C$	-	1.7	-	
		$T_j=150^{\circ}C$	-	1.7	-	
Gate-emitter threshold voltage	$V_{GE(th)}$	$I_C=0.6mA, V_{CE}=V_{GE}$	5.0	5.8	6.5	
Zero gate voltage collector current	I_{CES}	$V_{CE}=1200V,$ $V_{GE}=0V$				mA
		$T_j=25^{\circ}C$	-	-	0.2	
		$T_j=150^{\circ}C$	-	-	2.0	
Gate-emitter leakage current	I_{GES}	$V_{CE}=0V, V_{GE}=20V$	-	-	100	nA
Transconductance	g_{fs}	$V_{CE}=20V, I_C=15A$	-	10	-	S
Integrated gate resistor	R_{Gint}		none			Ω

Dynamic Characteristic

Input capacitance	C_{iss}	$V_{CE}=25V,$	-	1100	-	pF
Output capacitance	C_{oss}	$V_{GE}=0V,$	-	100	-	
Reverse transfer capacitance	C_{rss}	$f=1\text{ MHz}$	-	50	-	
Gate charge	Q_{Gate}	$V_{CC}=960V, I_C=15A$ $V_{GE}=15V$	-	85	-	nC
Internal emitter inductance measured 5mm (0.197 in.) from case	L_E		-	13	-	nH
Short circuit collector current ¹⁾	$I_{C(SC)}$	$V_{GE}=15V, t_{SC}\leq 10\mu s$ $V_{CC}=600V,$ $T_j=25^\circ C$	-	90	-	A

Switching Characteristic, Inductive Load, at $T_j=25^\circ C$

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	

IGBT Characteristic

Turn-on delay time	$t_{d(on)}$	$T_j=25^\circ C,$ $V_{CC}=600V, I_C=15A,$ $V_{GE}=0/15V,$ $R_G=56\Omega,$ $L_{\sigma}^{2)}=180nH,$ $C_{\sigma}^{2)}=39pF$ Energy losses include "tail" and diode reverse recovery.	-	50	-	ns
Rise time	t_r		-	30	-	
Turn-off delay time	$t_{d(off)}$		-	520	-	
Fall time	t_f		-	60	-	
Turn-on energy	E_{on}		-	1.3	-	mJ
Turn-off energy	E_{off}		-	1.4	-	
Total switching energy	E_{ts}		-	2.7	-	

Anti-Parallel Diode Characteristic

Diode reverse recovery time	t_{rr}	$T_j=25^\circ C,$	-	140	-	ns
Diode reverse recovery charge	Q_{rr}	$V_R=600V, I_F=15A,$	-	1.9	-	μC
Diode peak reverse recovery current	I_{rrm}	$di_F/dt=600A/\mu s$	-	17	-	A
Diode peak rate of fall of reverse recovery current during t_b	di_{rr}/dt		-	230	-	A/ μs

¹⁾ Allowed number of short circuits: <1000; time between short circuits: >1s.

²⁾ Leakage inductance L_{σ} and Stray capacity C_{σ} due to dynamic test circuit in Figure E.

Switching Characteristic, Inductive Load, at $T_j=150^\circ\text{C}$

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
IGBT Characteristic						
Turn-on delay time	$t_{d(on)}$	$T_j=150^{\circ}\text{C}$, $V_{CC}=600\text{V}$, $I_C=15\text{A}$, $V_{GE}=0/15\text{V}$, $R_G=56\Omega$ $L_{\sigma}^{1)}=180\text{nH}$, $C_{\sigma}^{1)}=39\text{pF}$	-	50	-	ns
Rise time	t_r		-	35	-	
Turn-off delay time	$t_{d(off)}$		-	600	-	
Fall time	t_f		-	120	-	
Turn-on energy	E_{on}	Energy losses include “tail” and diode reverse recovery.	-	2.0	-	mJ
Turn-off energy	E_{off}		-	2.1	-	
Total switching energy	E_{ts}		-	4.1	-	
Anti-Parallel Diode Characteristic						
Diode reverse recovery time	t_{rr}	$T_j=150^{\circ}\text{C}$ $V_R=600\text{V}$, $I_F=15\text{A}$, $di_F/dt=600\text{A}/\mu\text{s}$	-	330	-	ns
Diode reverse recovery charge	Q_{rr}		-	3.4	-	μC
Diode peak reverse recovery current	I_{rrm}		-	21	-	A
Diode peak rate of fall of reverse recovery current during t_b	di_{rr}/dt		-	190	-	A/ μs

¹⁾ Leakage inductance L_{σ} and Stray capacity C_{σ} due to dynamic test circuit in Figure E.

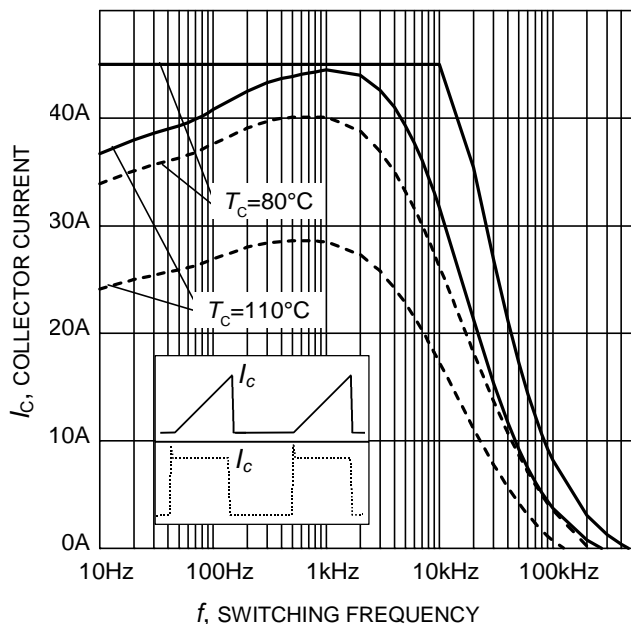


Figure 1. Collector current as a function of switching frequency
 $(T_j \leq 150^\circ\text{C}, D = 0.5, V_{CE} = 600\text{V}, V_{GE} = 0/+15\text{V}, R_G = 56\Omega)$

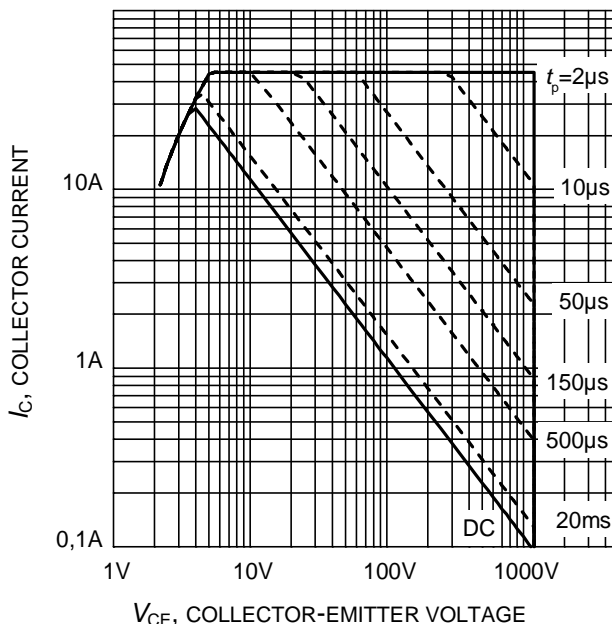


Figure 2. Safe operating area
 $(D = 0, T_C = 25^\circ\text{C}, T_j \leq 150^\circ\text{C}; V_{GE} = 15\text{V})$

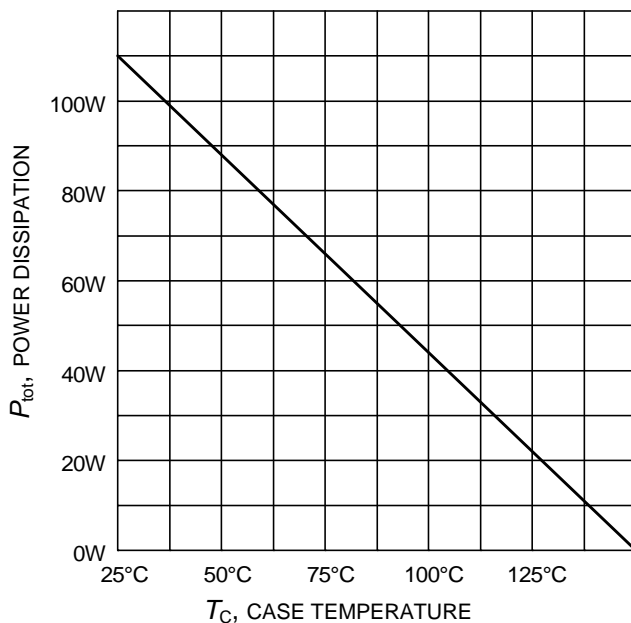


Figure 3. Power dissipation as a function of case temperature
 $(T_j \leq 150^\circ\text{C})$

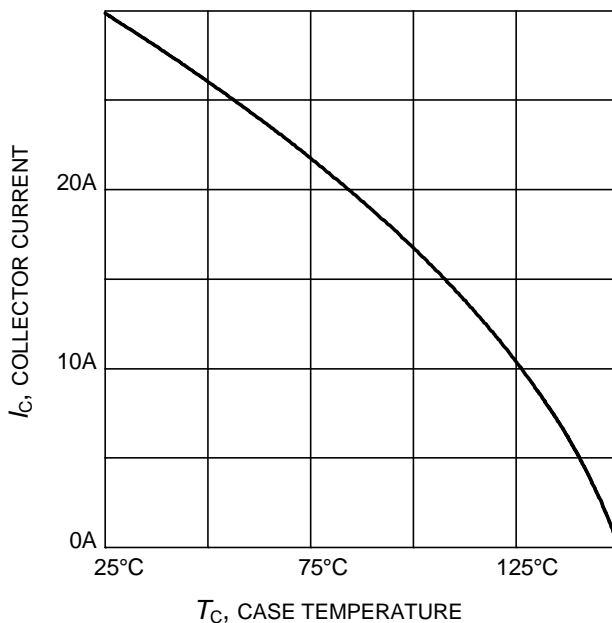


Figure 4. Collector current as a function of case temperature
 $(V_{GE} \geq 15\text{V}, T_j \leq 150^\circ\text{C})$

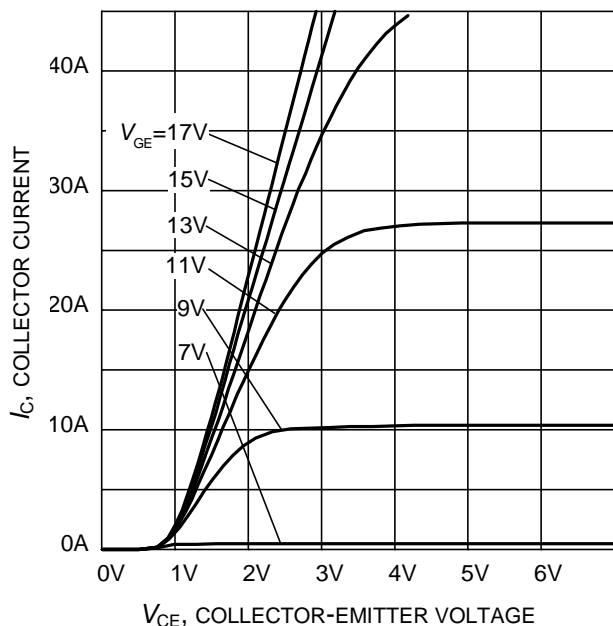


Figure 5. Typical output characteristic
($T_j = 25^\circ\text{C}$)

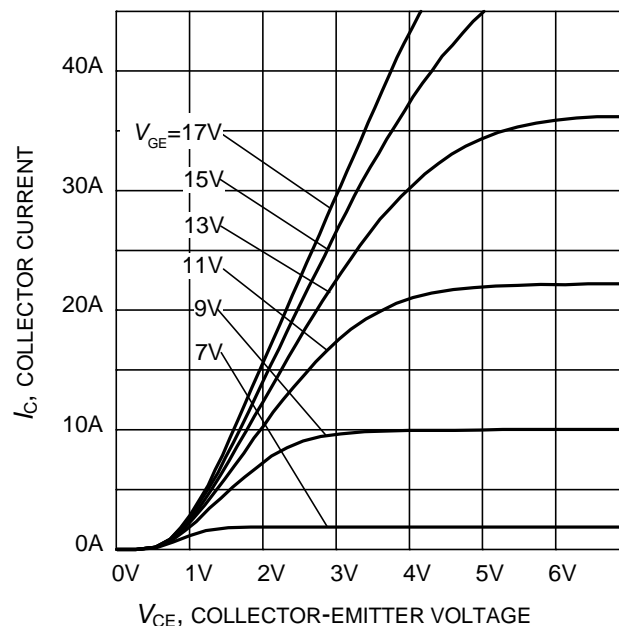


Figure 6. Typical output characteristic
($T_j = 150^\circ\text{C}$)

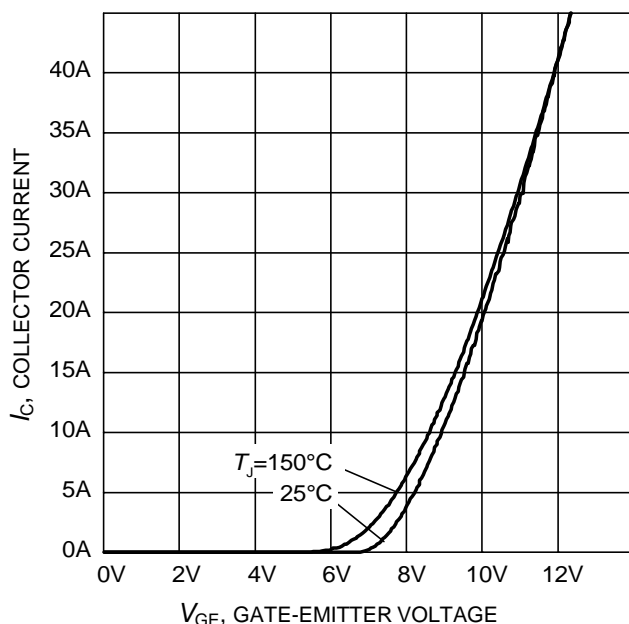


Figure 7. Typical transfer characteristic
($V_{CE} = 20\text{V}$)

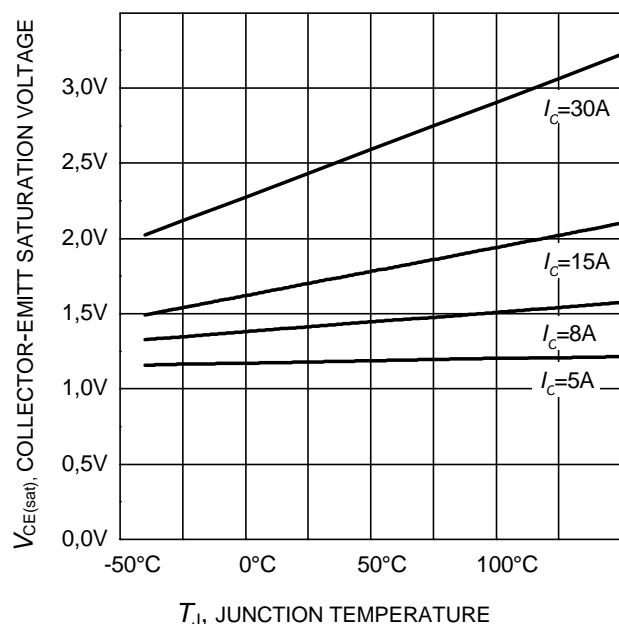


Figure 8. Typical collector-emitter saturation voltage as a function of junction temperature
($V_{GE} = 15\text{V}$)

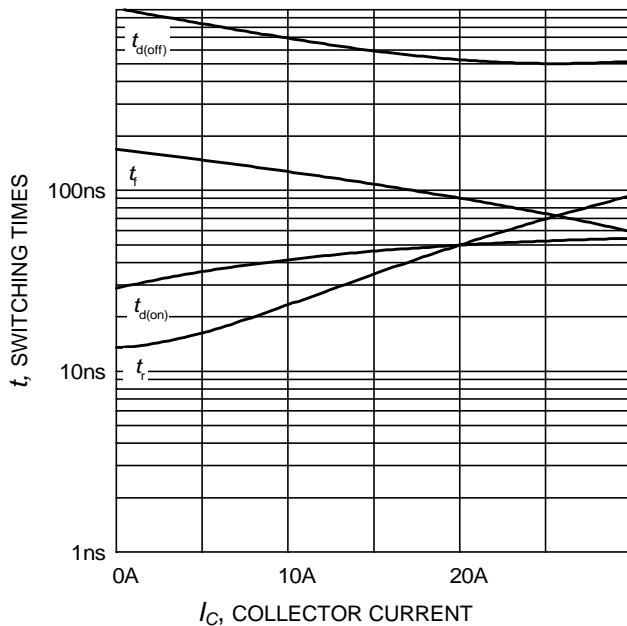


Figure 9. Typical switching times as a function of collector current
(inductive load, $T_J=150^\circ\text{C}$, $V_{CE}=600\text{V}$, $V_{GE}=0/15\text{V}$, $R_G=56\Omega$, Dynamic test circuit in Figure E)

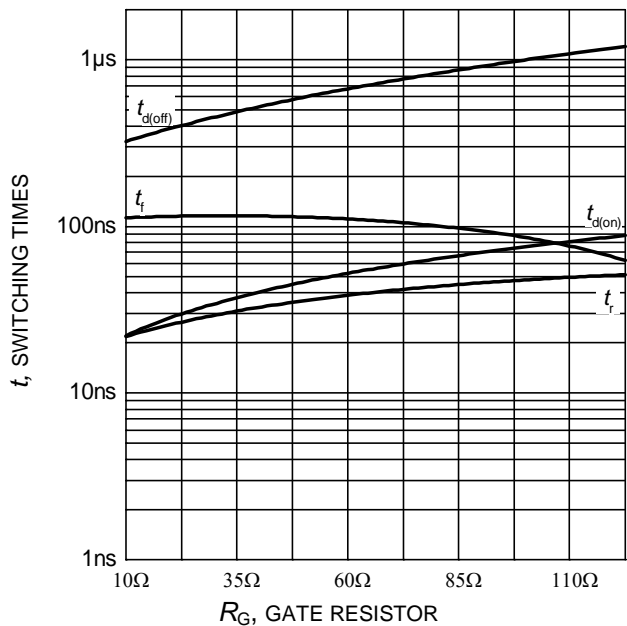


Figure 10. Typical switching times as a function of gate resistor
(inductive load, $T_J=150^\circ\text{C}$, $V_{CE}=600\text{V}$, $V_{GE}=0/15\text{V}$, $I_C=15\text{A}$, Dynamic test circuit in Figure E)

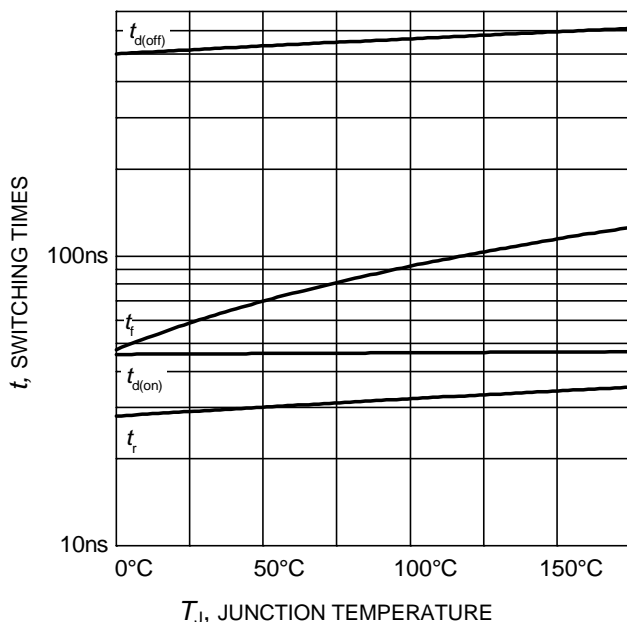


Figure 11. Typical switching times as a function of junction temperature
(inductive load, $V_{CE}=600\text{V}$, $V_{GE}=0/15\text{V}$, $I_C=15\text{A}$, $R_G=56\Omega$, Dynamic test circuit in Figure E)

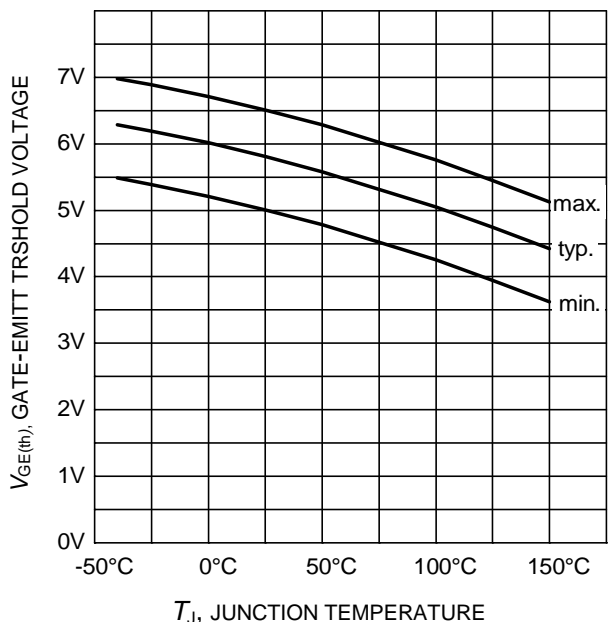


Figure 12. Gate-emitter threshold voltage as a function of junction temperature
($I_C = 0.6\text{mA}$)

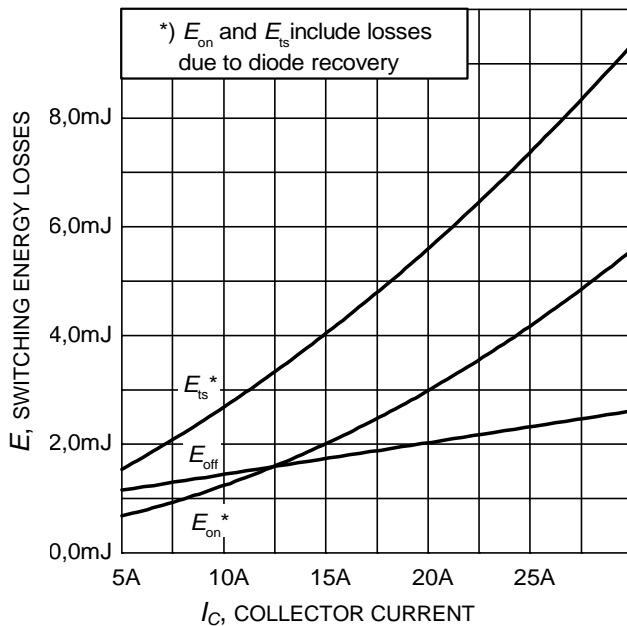


Figure 13. Typical switching energy losses as a function of collector current
(inductive load, $T_J=150^\circ\text{C}$, $V_{CE}=600\text{V}$, $V_{GE}=0/15\text{V}$, $R_G=56\Omega$, Dynamic test circuit in Figure E)

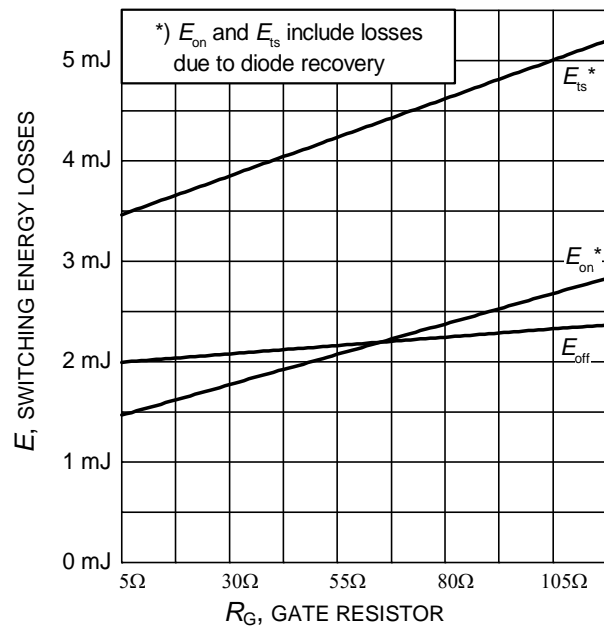


Figure 14. Typical switching energy losses as a function of gate resistor
(inductive load, $T_J=150^\circ\text{C}$, $V_{CE}=600\text{V}$, $V_{GE}=0/15\text{V}$, $I_C=15\text{A}$, Dynamic test circuit in Figure E)

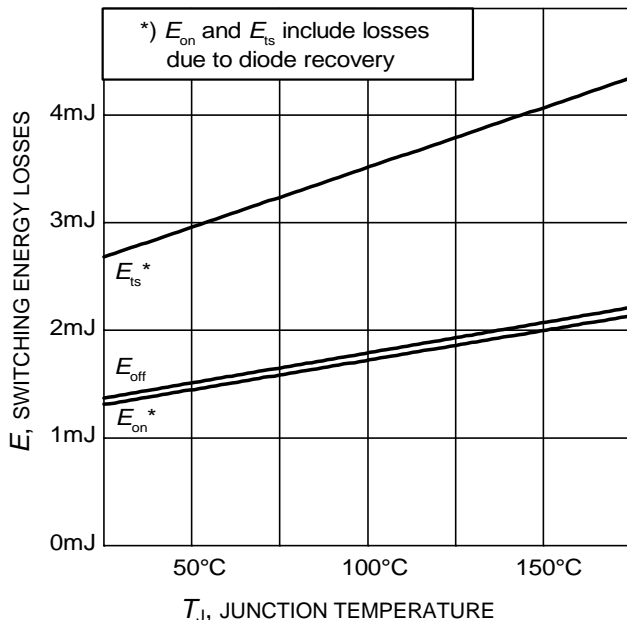


Figure 15. Typical switching energy losses as a function of junction temperature
(inductive load, $V_{CE}=600\text{V}$, $V_{GE}=0/15\text{V}$, $I_C=15\text{A}$, $R_G=56\Omega$, Dynamic test circuit in Figure E)

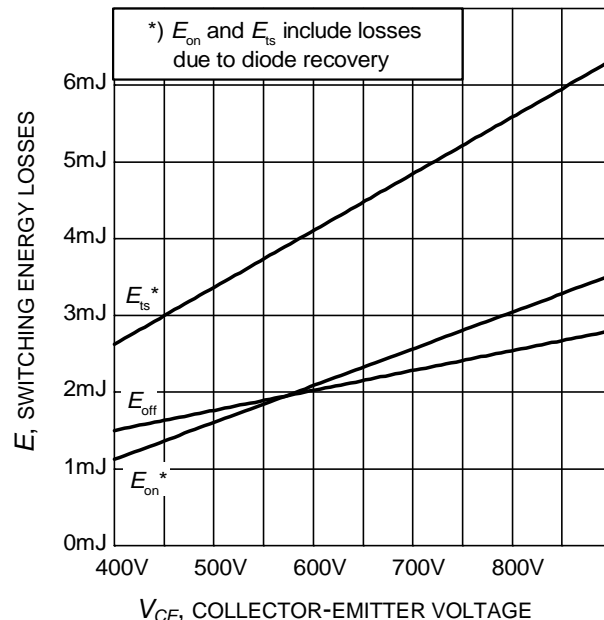


Figure 16. Typical switching energy losses as a function of collector emitter voltage
(inductive load, $T_J=150^\circ\text{C}$, $V_{GE}=0/15\text{V}$, $I_C=15\text{A}$, $R_G=56\Omega$, Dynamic test circuit in Figure E)

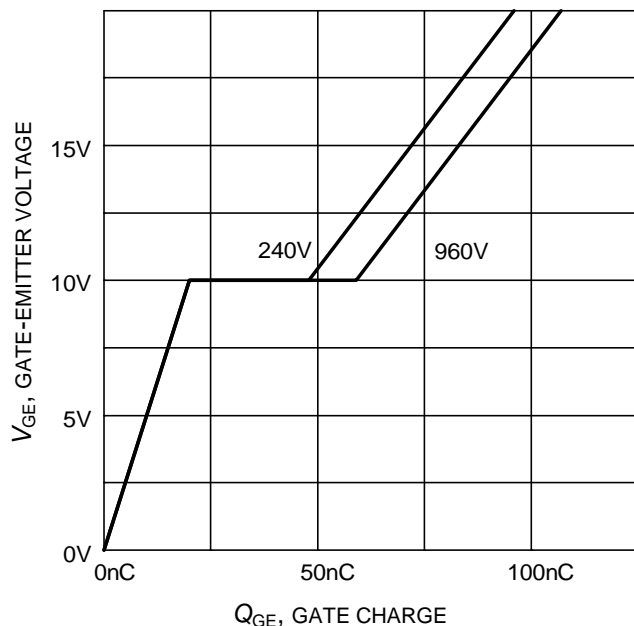


Figure 17. Typical gate charge
($I_C=15\text{ A}$)

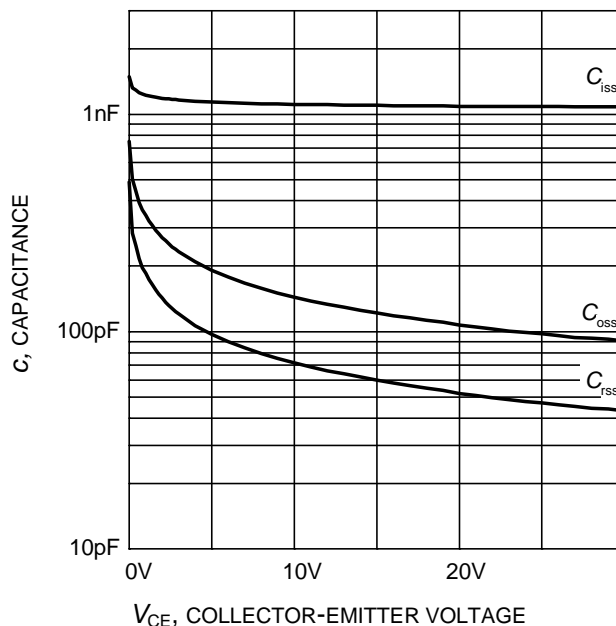


Figure 18. Typical capacitance as a function of collector-emitter voltage
($V_{GE}=0\text{V}$, $f=1\text{ MHz}$)

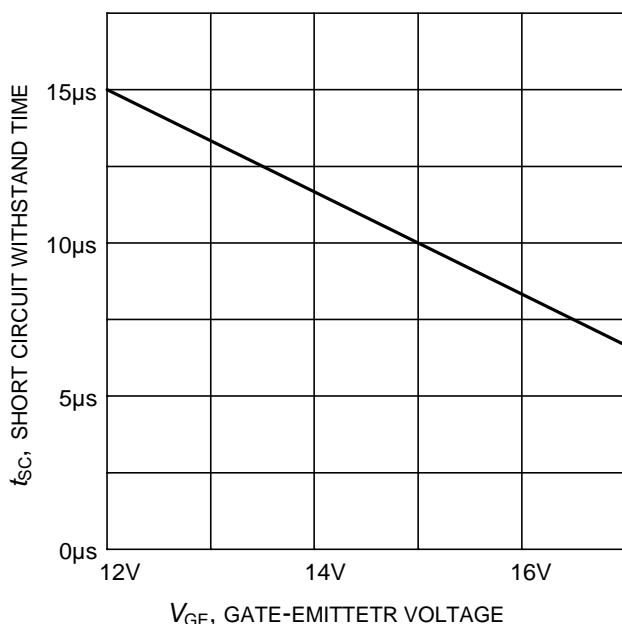


Figure 19. Short circuit withstand time as a function of gate-emitter voltage
($V_{CE}=600\text{V}$, start at $T_J=25^\circ\text{C}$)

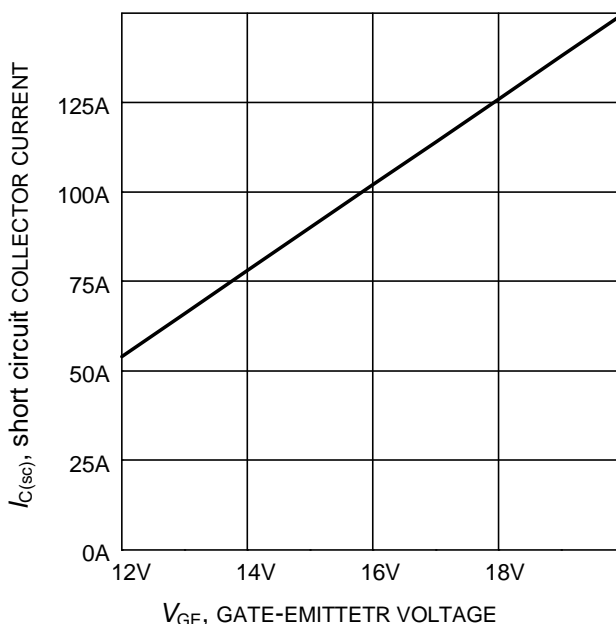


Figure 20. Typical short circuit collector current as a function of gate-emitter voltage
($V_{CE} \leq 600\text{V}$, $T_J \leq 150^\circ\text{C}$)

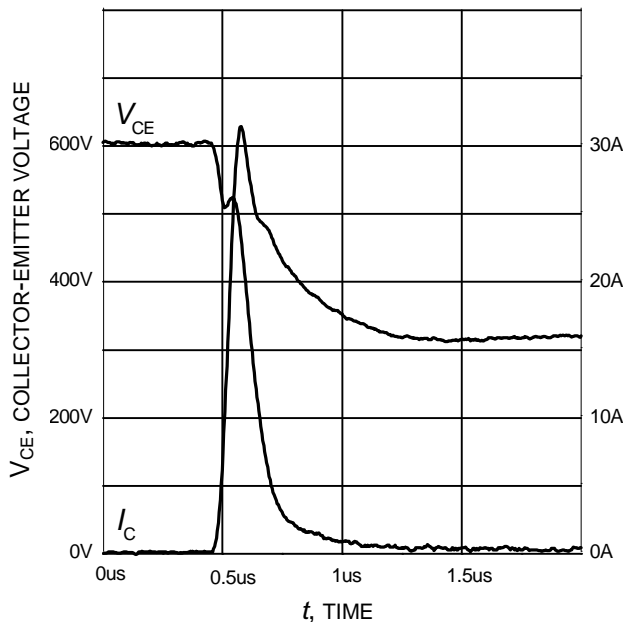


Figure 21. Typical turn on behavior
($V_{GE}=0/15V$, $R_G=56\Omega$, $T_j = 150^\circ C$,
Dynamic test circuit in Figure E)

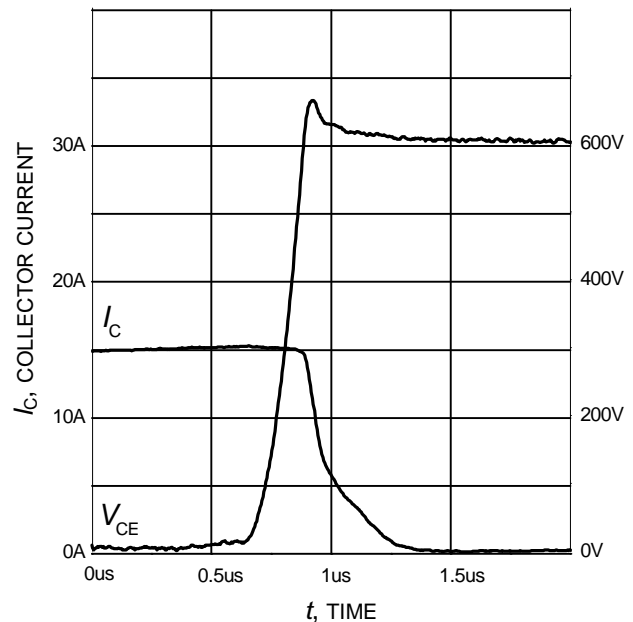


Figure 22. Typical turn off behavior
($V_{GE}=15/0V$, $R_G=56\Omega$, $T_j = 150^\circ C$,
Dynamic test circuit in Figure E)

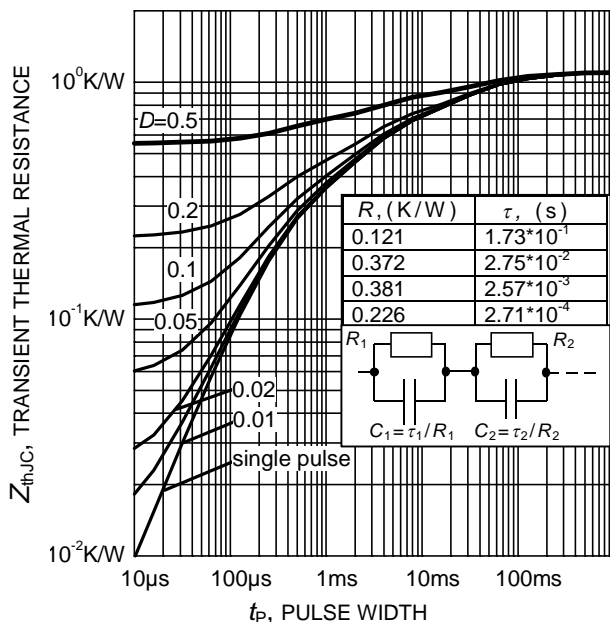


Figure 23. IGBT transient thermal resistance
($D = t_p / T$)

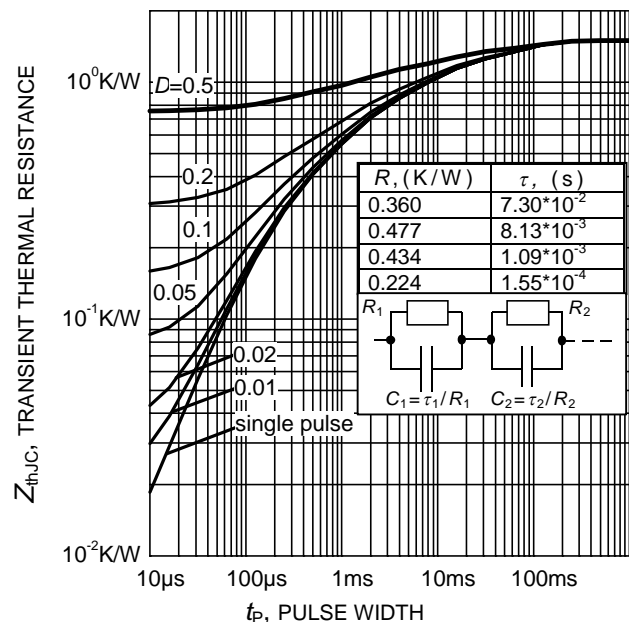


Figure 24. Diode transient thermal impedance as a function of pulse width
($D = t_p / T$)

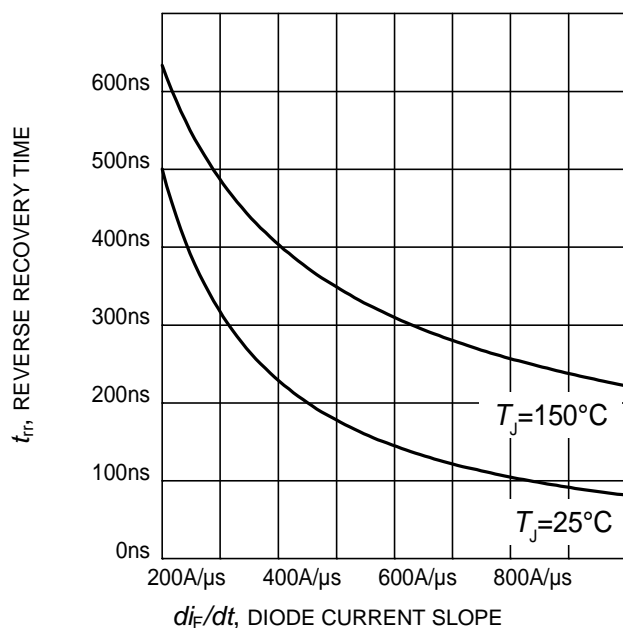


Figure 23. Typical reverse recovery time as a function of diode current slope
($V_R=600\text{V}$, $I_F=15\text{A}$,
Dynamic test circuit in Figure E)

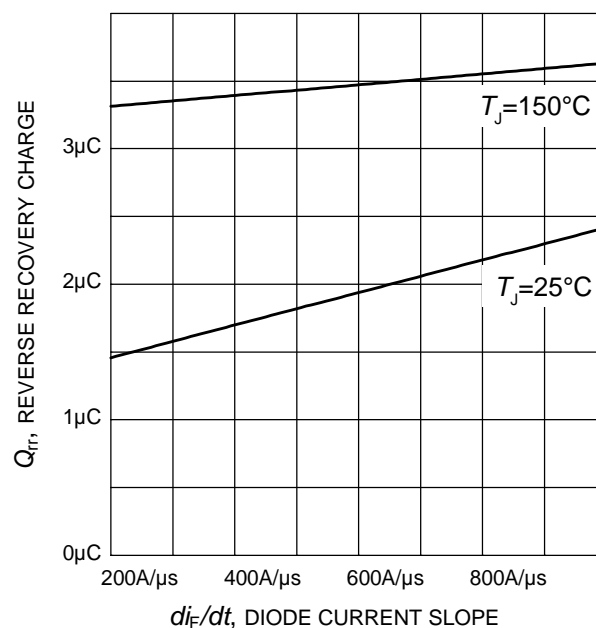


Figure 24. Typical reverse recovery charge as a function of diode current slope
($V_R=600\text{V}$, $I_F=15\text{A}$,
Dynamic test circuit in Figure E)

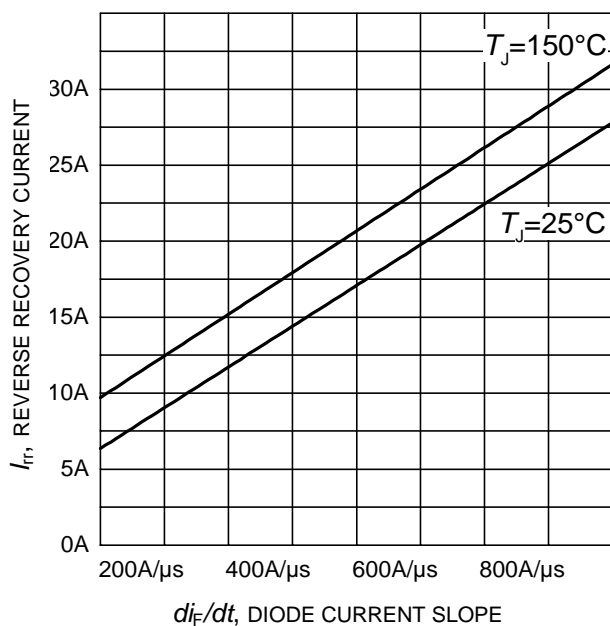


Figure 25. Typical reverse recovery current as a function of diode current slope
($V_R=600\text{V}$, $I_F=15\text{A}$,
Dynamic test circuit in Figure E)

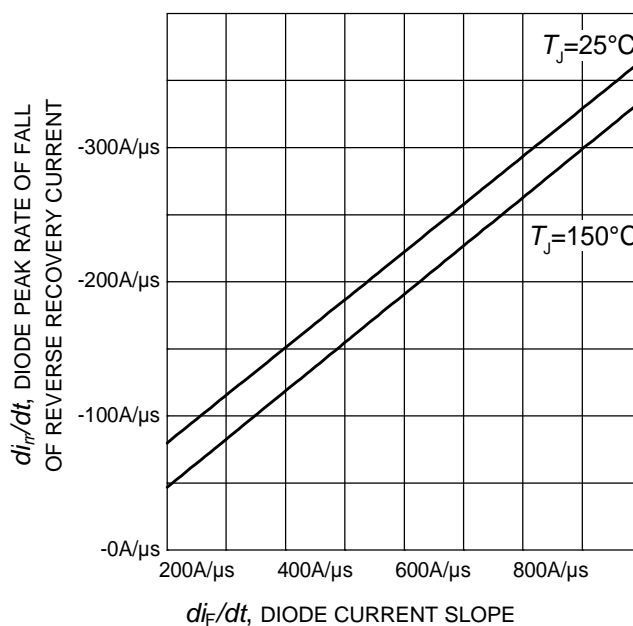


Figure 26. Typical diode peak rate of fall of reverse recovery current as a function of diode current slope
($V_R=600\text{V}$, $I_F=15\text{A}$,
Dynamic test circuit in Figure E)

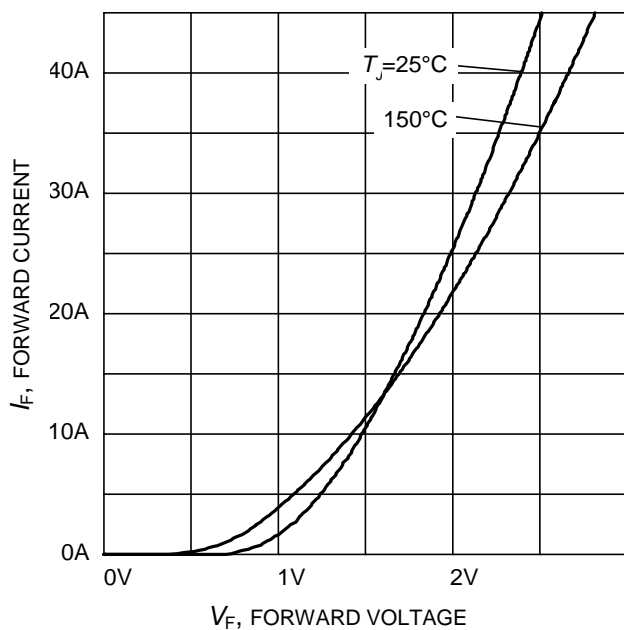


Figure 27. Typical diode forward current as a function of forward voltage

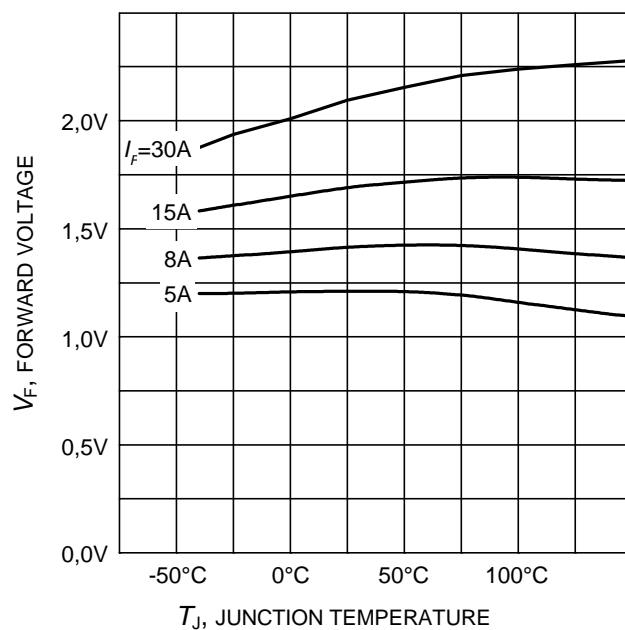
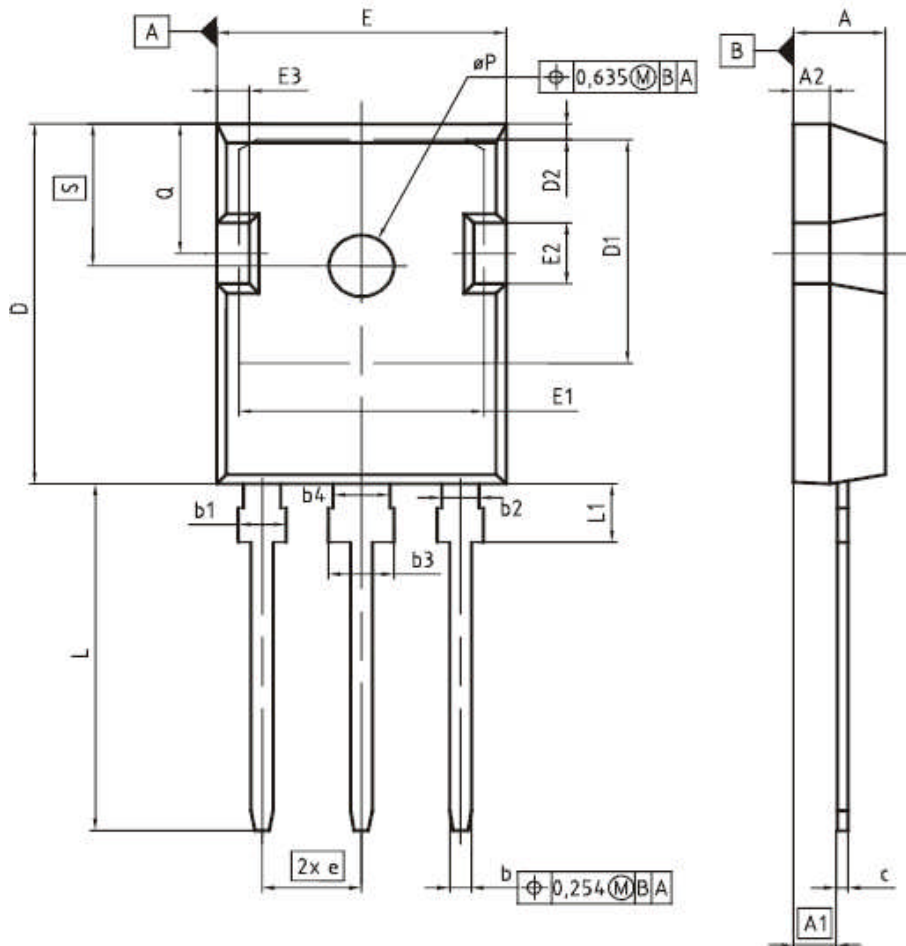
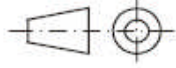


Figure 28. Typical diode forward voltage as a function of junction temperature

PG-TO247-3



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4,83	5,21	0,190	0,205
A1	2,27	2,54	0,089	0,100
A2	1,85	2,16	0,073	0,085
b	1,07	1,33	0,042	0,052
b1	1,90	2,41	0,075	0,095
b2	1,90	2,16	0,075	0,085
b3	2,87	3,38	0,113	0,133
b4	2,87	3,13	0,113	0,123
c	0,55	0,68	0,022	0,027
D	20,80	21,10	0,819	0,831
D1	16,25	17,65	0,640	0,695
D2	0,95	1,35	0,037	0,053
E	15,70	16,13	0,618	0,635
E1	13,10	14,15	0,516	0,557
E2	3,68	5,10	0,145	0,201
E3	1,00	2,60	0,039	0,102
e	5,44 (BSC)		0,214 (BSC)	
N	3		3	
L	19,80	20,32	0,780	0,800
L1	4,10	4,47	0,161	0,176
sP	3,50	3,70	0,138	0,146
Q	5,49	6,00	0,216	0,236
S	6,04	6,30	0,238	0,248

DOCUMENT NO. ZBB00003327
SCALE 0 5 5 7,5mm
EUROPEAN PROJECTION 
ISSUE DATE 09-07-2010
REVISION 05

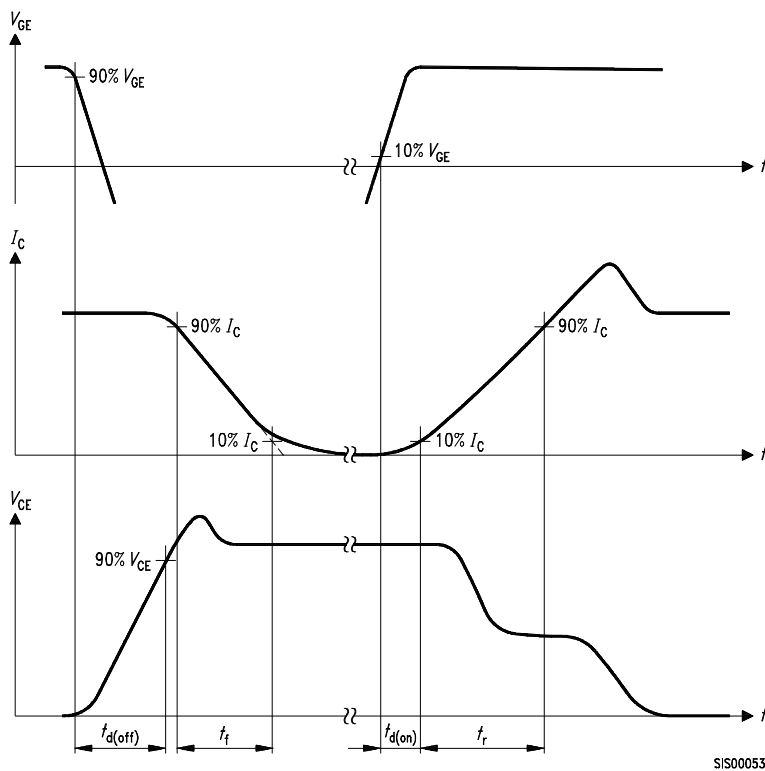


Figure A. Definition of switching times

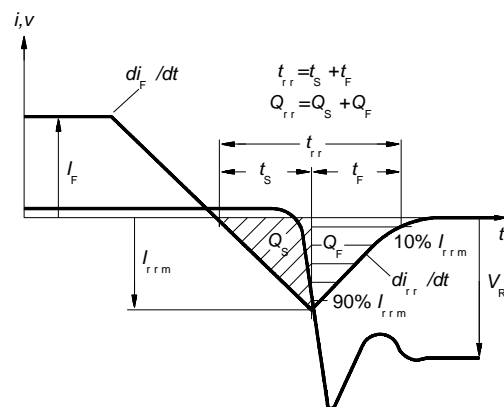


Figure C. Definition of diodes switching characteristics

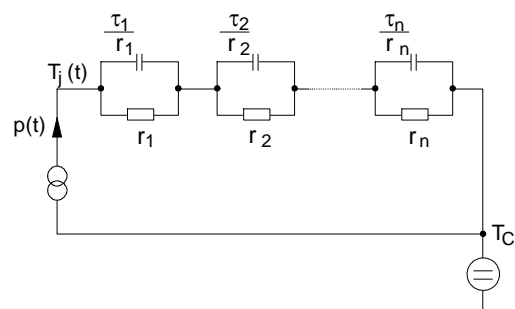


Figure D. Thermal equivalent circuit

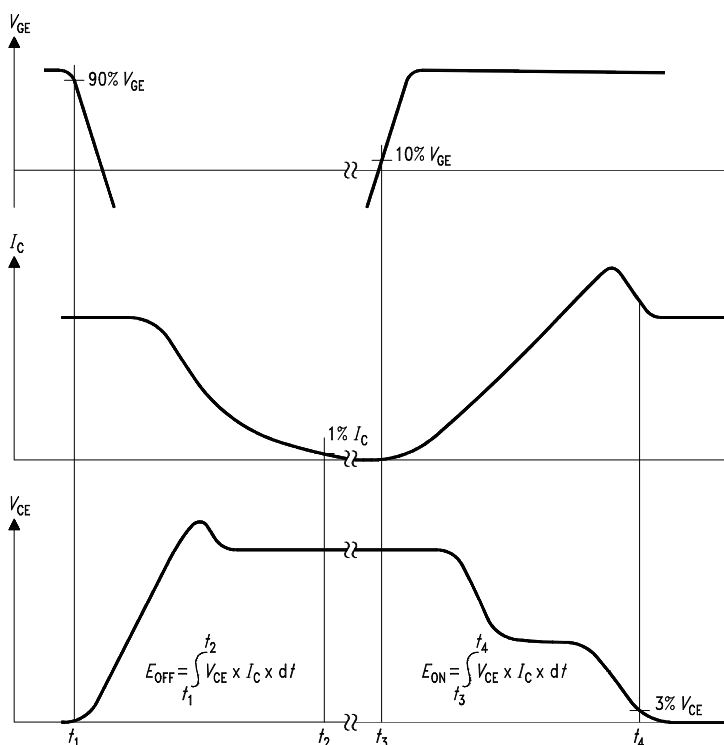
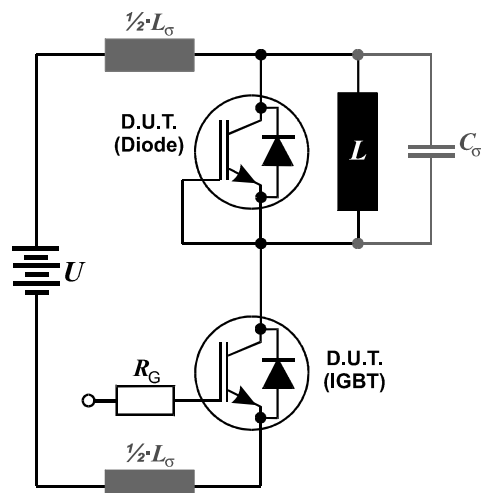


Figure B. Definition of switching losses


Figure E. Dynamic test circuit
Leakage inductance $L_\sigma = 180\text{nH}$
and Stray capacity $C_\sigma = 39\text{pF}$.

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Infineon Technologies AG
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